



SinglFuse™ SF-0402F Series Features

- Single blow fuse for overcurrent protection
- 1005 (EIA 0402) miniature footprint
- Fast-acting fuse
- UL listed
- RoHS compliant* and halogen free**
- Thin film chip fuse
- Surface mount packaging for automated assembly

SF-0402F Series - Fast Acting Surface Mount Fuses

Electrical Characteristics

Model	Rated Current (Amps)	Fusing Time	Resistance (mΩ) Typ.***	Rated Voltage	Breaking Capacity	Typical I²t (A²s)
SF-0402F050	0.50	Open within 1 min. at 200 % rated current	320	DC 24 V	DC24 V 35 A	0.00317
SF-0402F075	0.75		110			0.0049
SF-0402F080	0.80		120			0.00532
SF-0402F100	1.00		90			0.00724
SF-0402F125	1.25		67			0.01344
SF-0402F150	1.50		51			0.01356
SF-0402F160	1.60		46			0.01672
SF-0402F200	2.00		33			0.01983
SF-0402F250	2.50		25			0.03763
SF-0402F300	3.00		20			0.05427
SF-0402F315	3.15		19			0.06304
SF-0402F400	4.00		16			0.0896

***Resistance value was measured with less than 10 % of rated current.

Reliability Testing

Parameter	Requirement	Test Method
Carrying Capacity	No fusing	Rated current, 4 hours
Fusing Time	Within 1 minute	200 % of its rated current
Interrupting Ability	No mechanical damages	After the fuse is interrupted, rated voltage applied for 30 seconds again
Bending Test	No mechanical damages	Distance between holding points: 90 mm, Bending: 3 mm, 1time, 30 seconds
Resistance to Solder Heat	±20 %	260 °C ±5 °C, 10 seconds ±1 second
Solderability	95 % coverage minimum	235 °C ±5 °C, 2 ±0.5 second 245 °C ±5 °C, 2 ±0.5 second (lead free)
Temperature Rise	<75 °	100 % of its rated current, measure of surface temperature
Resistance to Dry Heat	±20 %	105 °C ±5 °C, 1000 hours
Resistance to Solvent	No evident damage on protective	23 °C ±5 °C of isopropyl alcohol, 90 seconds coating and marking
Residual Resistance	10k W or more	Measure DC resistance after fusing
Thermal Shock	DR < 10 %	-20 °C / +25 °C / +125 °C / +25 °C, 10 cycles

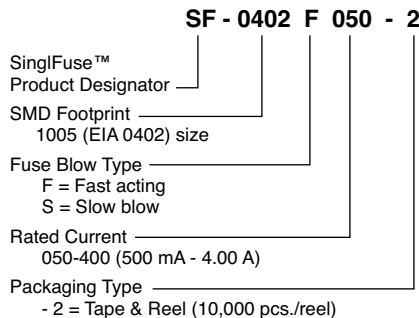
Typical Part Marking

Represents total content. Layout may vary.



RATING CURRENT (A)
 F = 0.50 N = 1.60
 * = 0.75 S = 2.00
 K = 0.80 T = 2.50
 L = 1.00 3 = 3.00
 M = 1.25 U = 3.15
 P = 1.50 W = 4.00

How to Order



Asia-Pacific:
 Tel: +886-2 2562-4117
 Fax: +886-2 2562-4116

Europe:
 Tel: +41-41 768 5555
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The Americas:
 Tel: +1-951 781-5500
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www.bourns.com

* RoHS Directive 2002/95/EC Jan 27 2003 including Annex.

** Bourns is using the definition that appears to be the prevalent definition used as the industry standard at this time. The Bourns definition of "halogen-free" is: Bromine (Br) content: ≤ 900 ppm; Chlorine (Cl) content: ≤ 900 ppm; Total Br + Cl content: ≤ 1500 ppm.

"SinglFuse" is a trademark of Bourns, Inc.

Specifications are subject to change without notice.

The device characteristics and parameters in this data sheet can and do vary in different applications and actual device performance may vary over time. Users should verify actual device performance in their specific applications.

SinglFuse™ SF-0402F Series Applications

- Portable memory
- LCD monitors
- Disk drives
- PDAs
- Digital cameras
- DVDs
- Cell phones
- Rechargeable battery packs
- Battery chargers
- Set top boxes
- Industrial controllers

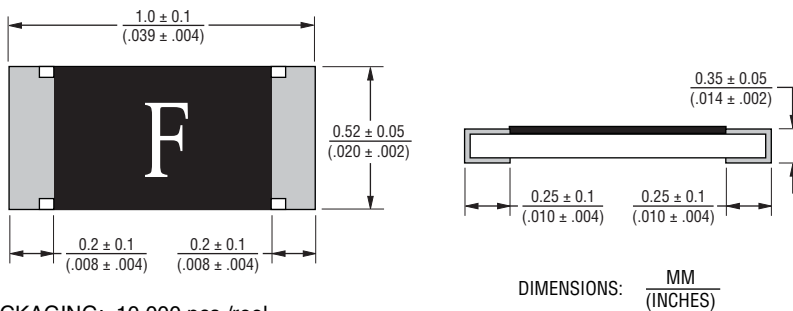
SF-0402F Series - Fast Acting Surface Mount Fuses BOURNS®

Solder Reflow Recommendations



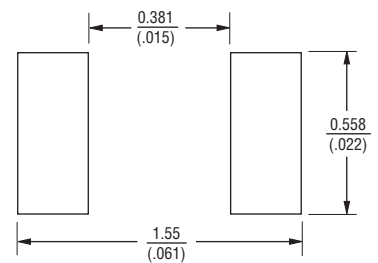
PEAK: 250 +0/-5 °C, 5 seconds
 PRE-HEATING ZONE: 150 to 180 °C, 90 ± 30 seconds
 SOLDERING ZONE: 230 °C or higher, 30 ± 10 seconds

Product Dimensions



PACKAGING: 10,000 pcs./reel

Recommended Pad Layout

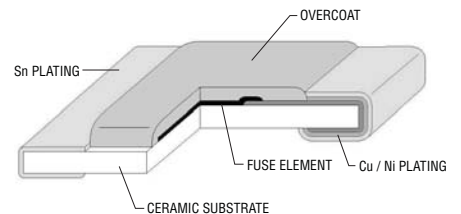


Thermal Derating Curve



Operating Temperature.....-40 °C to +105 °C
 Storage Conditions
 Temperature +5 °C to +35 °C
 Humidity.....40 % to 75 %
 Shelf Life..... 2 years from manufacturing date

Construction & Material Content



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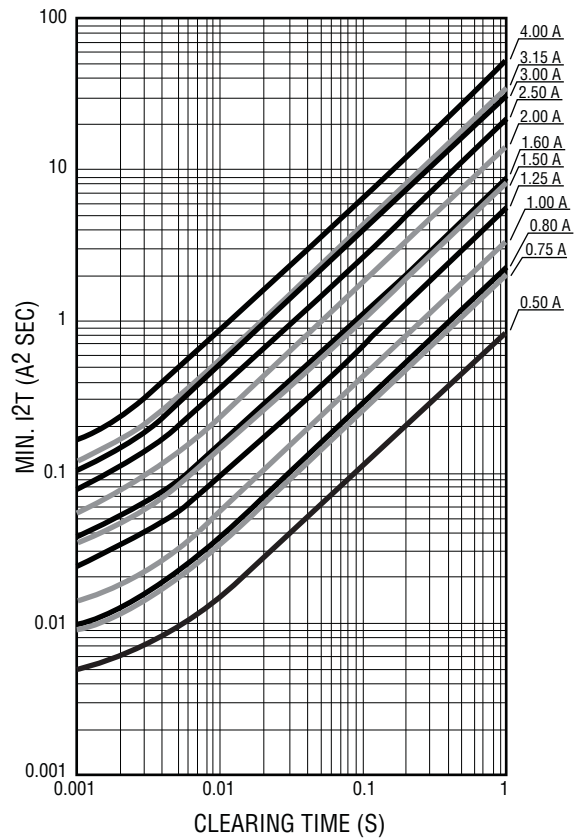
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Average Time Current Curves



Minimum I²T V Clear Time Curves



REV. D 03/13

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SF-0402F Series Tape and Reel Specifications

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Tape Dimensions	SF-0402F Series per EIA 481-2
W	$\frac{8.0 \pm 0.2}{(.315 \pm .008)}$
P ₀	$\frac{4.0 \pm 0.1}{(.157 \pm .004)}$
P ₁	$\frac{2.0 \pm 0.1}{(.079 \pm .004)}$
P ₂	$\frac{2.0 \pm 0.05}{(.079 \pm .002)}$
A	$\frac{0.7 \pm 0.05}{(.028 \pm .002)}$
B	$\frac{1.2 \pm 0.05}{(.047 \pm .002)}$
F	$\frac{3.5 \pm 0.05}{(.138 \pm .002)}$
E	$\frac{1.75 \pm 0.1}{(.069 \pm .004)}$
D ₀	$\frac{1.5 \pm 0.1}{(.059 \pm .004)}$
T	$\frac{0.45 \pm 0.01}{(.018 \pm .004)}$
Reel Dimensions	
A	$\frac{180 \pm 0/-3.0}{(7.087 \pm 0/-0.118)}$
B Min.	$\frac{60.0}{(2.362)}$
C	$\frac{13.0 \pm 1.0}{(.512 \pm .039)}$
W	$\frac{9.0 \pm 1.0}{(.354 \pm .039)}$
T	$\frac{11.4 \pm 2.0}{(.449 \pm .079)}$



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Нашей специализацией является поставка электронной компонентной базы двойного назначения, продукции таких производителей как XILINX, Intel (ex.ALTERA), Vicor, Microchip, Texas Instruments, Analog Devices, Mini-Circuits, Amphenol, Glenair.

Сотрудничество с глобальными дистрибьюторами электронных компонентов, предоставляет возможность заказывать и получать с международных складов практически любой перечень компонентов в оптимальные для Вас сроки.

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Система менеджмента качества компании отвечает требованиям в соответствии с ГОСТ Р ИСО 9001, ГОСТ РВ 0015-002 и ЭС РД 009

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